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What is claimed is:

1. A method for micromachining a structure, said method comprising selectively removing at least a portion of the structure by chemical mechanical polishing, wherein the structure thus formed is at least partially non-planar.

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- 2. The method of claim 1 wherein the structure is formed on an essentially planar substrate.
- 3. The method of claim 1 wherein said chemical mechanical polishing step is conducted using a chemical mechanical polishing apparatus that includes a polishing pad.
 - 4. The method of claim 3 wherein said removal is by a combination of chemical etch and mechanical polishing.
- 15 5. The method of claim 4 wherein said mechanical polishing is controlled by varying at least one characteristic of the polishing pad.
 - 6. The method of claim 5 wherein said characteristic of the polishing pad is stiffness.
- 7. The method of claim 6 wherein said stiffness is manipulated by downforce on the pad, rotational velocity of the pad, acceleration velocity of the pad, local curvature of the pad, or combinations thereof.

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- 8. The method of claim 1 wherein a concave structure is formed.
- 9. The method of claim 1 wherein a convex structure is formed.
- 5 10. The method of claim 1 wherein a rounded structure is formed.
 - 11. The method of claim 7 wherein local curvature on the pad is provided be preshaped asperities.
- 10 12. The method of claim 7 wherein local curvature on the pad is provided by bumps under the pad.
- 13. The method of claim 1 wherein the structure includes a highest point and a lowest point, and wherein height differential between the highest point and the lowest point is
 15 0.5 microns or greater.
 - 14. The method of claim 1 wherein the structure includes a highest point and a lowest point, and wherein height differential between the highest point and the lowest point is 1 micron or greater.

15. The method of claim 1 wherein the structure includes a highest point and a lowest point, and wherein height differential between the highest point and the lowest point is 2 microns or greater.

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- 16. A partially non-planar structure fabricated by the method of claim 1.
- 17. A microlens array fabricated by the method of claim 1.
- 5 18. An optical fiber array connector fabricated by the method of claim 1.